

Amendment to Claims: This Listing of Claims will replace all prior versions and listings of claims in the Application.

Please cancel claims 1-13, and add claims 24 – 57.

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**LISTING OF CLAIMS**

Claims 1-13 (Canceled)

14. (Withdrawn) A method of joining at least two adherends comprising the steps of:

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a) applying a layer of from about 1.1 mm to about 7 mm of moisture curable adhesive comprising a polymer or copolymer including reactive silicon end groups to at least one adherend of two adherends;

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b) maintaining the two adherends in non-contact with each other until the adhesive begins to develop a sufficient tack to hold the at least two adherends together; and

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c) first contacting and then forming a bond between the two adherends with the adhesive.

15. (Withdrawn) The method of joining the at least two adherends in claim 14, wherein the two adherends are maintained in non-contact with each other for less than about 20 minutes.

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16. (Withdrawn) The method of joining the at least two adherends in claim 15, further comprising the step of repositioning the two adherends with respect to each other greater than about 5 minutes after they are first contacted.

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17. (Withdrawn) The method of joining the at least two adherends in claim 16, wherein the two adherends can be repositioned with respect to each other greater than about 20 minutes after they are first contacted.

18. (Withdrawn) The method of joining the at least two adherends in claim 17, wherein the bond between the two adherends is 90 % cured in less than 8 hours.

5 19. (Withdrawn) A method of joining at least two adherends comprising the steps of:

a) applying a layer of moisture curable adhesive comprising a polymer or copolymer including reactive silicon end groups to at least one adherend of two adherends;

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b) maintaining the two adherends in non-contact with each other for less than about 20 minutes until the adhesive begins to cure; and

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c) first contacting then forming a bond between the two adherends with the adhesive

wherein the two adherends can be repositioned after contacting and the adhesive reaches an initial cure in less than thirty minutes.

20 20. (Withdrawn) The method of joining the at least two adherends in claim 19, wherein the two adherends are maintained in non-contact with each other for less than about 20 minutes.

25 21. (Withdrawn) The method of joining the at least two adherends in claim 20, further comprising the step of repositioning the two adherends with respect to each other more than 5 minutes after they are first contacted.

30 22. (Withdrawn) The method of joining the at least two adherends in claim 21, wherein the two adherends can be repositioned with respect to each other more than 20 minutes after they are first contacted.

23. (Withdrawn) The method of joining the at least two adherends in claim 22, wherein the bond between the two adherends is 90 % cured in less than 8 hours.

24. (New) A moisture curable adhesive, comprising:

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- a) a polymer or copolymer having reactive silicon end groups;
- b) from about from about 5 to about 90 weight percent of a filler, which includes fumed silica having a surface area of less than 200 m<sup>2</sup>/gram ; and
- c) from about 0.01 to about 10 percent by weight of a dehydrating agent.

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25. (New) The moisture curable adhesive in claim 24, wherein the adhesive has a viscosity of from about 1,000 to about 500,000 centipoise.

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26. (New) The moisture curable adhesive in claim 24, wherein the adhesive has a viscosity of from about 1,000 to about 200,000 centipoise.

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27. (New) The moisture curable adhesive in claim 24, wherein the amount of filler is from about 20 to about 85 percent by weight.

28. (New) The moisture curable adhesive in claim 24, wherein the amount of filler is from about 35 to about 85 percent by weight.

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29. (New) The moisture curable adhesive in claim 24, wherein the amount of filler is from about 43 to about 85 percent by weight.

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30. (New) The moisture curable adhesive in claim 24, wherein the amount of filler is from about 60 to about 85 percent by weight.

31. (New) The moisture curable adhesive in claim 24, wherein the filler includes a filler having a surface area of less than 150 m<sup>2</sup>/gram

32. (New) The moisture curable adhesive in claim 24, wherein the filler includes a  
filler having a surface area of less than 75 m<sup>2</sup>/gram

5 33. (New) The moisture curable adhesive in claim 24, wherein the filler includes a  
filler having a surface area of less than 50 m<sup>2</sup>/gram

34. (New) The moisture curable adhesive in claim 24, wherein the filler with the  
surface area less than 250 m<sup>2</sup>/grams is fumed amorphous silica.

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35. (New) The moisture curable adhesive in claim 24, which includes calcium  
carbonate as a filler.

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36. (New) The moisture curable adhesive in claim 24 which has filler selected from:  
zinc oxide; reinforcing, semi-reinforcing, and non-reinforcing carbon blacks;  
white carbon; expanded graphite powders; powdery graphite; crystalline silica;  
molten silica; silicates; chalk; calcium carbonate including limestone; talc; mica;  
alumina; aluminum hydroxide; zirconia; titanium dioxide; wollastonite; feldspar;  
aluminum silicate; solid and hollow ceramic microspheres hollow spheres,  
ceramic and plastic; metal powders and microbeads; wood flour; dolomite;  
20 organic or inorganic pigments, or combinations thereof.

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37. (New) The moisture curable adhesive in claim 24, wherein the adhesive further  
comprises at least one of a catalyst; anti-oxidants, lubricants, extenders, biocides,  
adhesion promoters, UV absorbers and stabilizers.

38. (New) The moisture curable adhesive in claim 24, wherein the catalyst is present  
in an amount from about 0.01 to about 2.5 percent by weight.

39. (New) The moisture curable adhesive in claim 24, wherein the dehydrating agents is selected from vinyl trimethoxysilane, any vinyl alkoxy silane, or inorganic or organic zeolites.

5 40. (New) The moisture curable adhesive in claim 24, wherein the adhesion promoter is present in an amount of about 0.01 to about 5 % by weight.

41. (New) The moisture curable adhesive in claim 24, wherein the anti-oxidant is present in an amount from about 0.01 to about 4 % by weight.

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42. (New) The moisture curable adhesive in claim 24, wherein the polymer or copolymer having reactive silicon end groups is present in an amount of about 10 to about 50 percent by weight

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43. (New) A moisture curable adhesive, comprising:

- a) a polymer or copolymer having reactive silicon end groups;
- b) from about .01 to about 50 percent by weight of a clear filler that will not substantially interfere with the production of clear adhesive selected from:
  - i) fumed silica with a surface area of less than 150 m<sup>2</sup>/gram, or a clear filler having a surface area from 75 to less than 250 m<sup>2</sup>/gram where the viscosity of the adhesive is in the range of 1,000 to about 200,000 centipoise; and
- c) from about 0.01 to about 10 percent by weight of a dehydrating agent

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44. (New) The moisture curable adhesive in claim 43, wherein the adhesive has a viscosity from about 1,000 to about 200,000 centipoise.

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45. (New) The moisture curable adhesive in claim 43, wherein the glass transition temperature of the adhesive is less than about -20 °C.

5 46. (New) The moisture curable adhesive in claim 43, wherein the service temperature range of the adhesive is from about -60°C to about 160 °C.

47. (New) The moisture curable adhesive in claim 43, wherein the clear filler is fumed amorphous silica.

10 48. (New) The moisture curable adhesive in claim 43, wherein the polymer or copolymer having reactive silicon end groups is present in an amount of about 50 to about 90 percent by weight.

15 49. (New) The moisture curable adhesive in claim 43, wherein the polymer or copolymer having reactive silicon end groups is present in an amount of about 65 to about 80 percent by weight and the polymer or copolymer is selected from polyalkyl oxide; any polyalkane, alkene, or alkyne; polymers of substituted alkyl monomers of styrene; acrylics or any polymer or copolymer that can be prepared with the silyl, reactive silicon, end groups or combinations thereof, and where the polymer or copolymer has reactive silicon end groups selected from triethoxysilane, methyldiethoxysilane, trisilanol, any alkoxy silane, substituted silane, multi-silanol, or combinations thereof.

20 50. (New) The moisture curable adhesive in claim 43, wherein the amount of filler is from about 5 to about 20 percent by weight.

25 51. (New) The moisture curable adhesive in claim 43, wherein the filler includes a filler having a surface area of less than 75 m<sup>2</sup>/gram

52. (New) The moisture curable adhesive in claim 43, wherein the filler includes a blend of fillers one having a surface area of 50 m<sup>2</sup>/gram and another one having a surface area of 110 m<sup>2</sup>/gram.

5 53. (New) The moisture curable adhesive in claim 43, wherein the adhesive further comprises at least one of a catalyst; anti-oxidants, lubricants, extenders, biocides, adhesion promoters, UV absorbers and stabilizers.

10 54. (New) The moisture curable adhesive in claim 43, wherein the catalyst is present in an amount from about 0.01 to about 2.5 percent by weight.

15 55. (New) The moisture curable adhesive in claim 43, wherein the dehydrating agents is selected from vinyl trimethoxysilane, any vinyl alkoxy silane, or inorganic or organic zeolites.

56. (New) The moisture curable adhesive in claim 43, wherein the adhesion promoter is present in an amount of about 0.01 to about 5 % by weight.

20 57. (New) The moisture curable adhesive in claim 24, wherein the anti-oxidant is present in an amount from about 0.01 to about 4 % by weight.